

Epoxy Resin 702AB

I. Statement of purpose

Epoxy Resin 702AB is an epoxy resin bonding adhesive cured at room temperature and low temperature, with fast curing time, high adhesive strength and can be cured at extra temperature. It is specially used for metal bonding, electronic product bonding, wood bonding, hard material bonding and mold filling, as well as insulation of other electronic parts, moisture-proof potting, and confidentiality sealing.

II. Pre-sclerotic properties.

	A glue702A	curing agent702B
Color:	colorless and transparen	colorless and transparen
weight:	<u>1.15</u>	<u>1.05</u>
Viscosity 25℃:	<u>8000-12000CPS</u>	<u>5500-8500CPS</u>

III. Conditions of use

- 1)mixing ratio: A: B=100: 100 (weight ratio)
- 2)hardening condition: 25℃×1H or 55℃×10 min (2g)
- 3)usable time: 25℃×10min (10g)

IV. Methods of use.

1. Working environment: keep the glue container clean, A, B components strictly according to the weight ratio, accurate weighing, clockwise along the inner wall of the container to mix well and stand for 3-5 minutes after use.
2. Depending on the operating time and dosage of the glue, to avoid waste. When the temperature is lower than 15 ℃, please preheat the A glue to 30 ℃ before glue mixing, easy to operate (low temperature A glue will become thicker); after use must be sealed barrel lid, to avoid moisture absorption caused by the product scrap.
3. When the relative humidity is greater than 85%, the surface of the cured material is easy to absorb water in the air, forming a layer of white mist, so when the relative humidity is greater than 85%, it is not suitable for room temperature curing, it is recommended to use the heating curing.

V. Properties after hardening

1)hardness:	shore D	<u><78</u>
2)withstand voltage:	KV/mm	22
3)bending strength:	Kg/mm2	27
4)volume resistance:	Ohm3	1x10 ¹⁵
5)surface resistance:	Ohmm2	5X10 ¹⁵
6) thermal conductivity:	W/M.K	0.56
7) electrostatic losses:	1KHZ	0.42
8) heat distortion temperature:	℃	140
9) water absorption:	%	<0.15
10)compressive strength:	Kg/mm2	11.4

The above performance data are typical data measured in a laboratory environment with a temperature of 25℃ and a humidity of 70%, and are for customers' reference only.